

## ABSTRACT OF THE DISCLOSURE

A resin-encapsulated semiconductor device includes a die pad, a semiconductor chip mounted on the die pad, and a group of leads. The group of leads include at least three kinds of leads, including first, second and third leads. While the first lead and the third lead are connected to each other upon production of the lead frame, the first lead and the third lead are separated from each other in a subsequent step. Moreover, a thin metal wire for connecting an electrode of the semiconductor chip to the bonding pad of each lead, and an encapsulation resin for encapsulating the semiconductor chip, the leads, the thin metal wire, etc., are provided. The pad of each lead is exposed on a surface of the encapsulation resin so that the pad can function as an external terminal.

100-200-300-400-500-600-700-800-900-1000

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